

Re: PCB layout for ADC

3. Any thoughts on doing GND copper pours for the top & bottom layers?
The previous design did not use any copper pours for the routing layers.

One inner-layer ground plane should be enough. Surface fill-in pours are mostly cosmetic.

4. The main board already provides "bulk" 10 uF caps for the power rails. Should we add 10uF caps onto the daughterboard as well or just not worry about it?

Better to use surfmount ceramics, close to the adc power pins, 0.33